## **Refine Search**

## Search Results -

Terms	Documents
L2 and amino acid	. 90

US Pre-Grant Publication Full-Text Database

US Patents Full-Text Database

US OCR Full-Text Database

Database: EPO Abstracts Database

JPO Abstracts Database

**Derwent World Patents Index** 

IBM Technical Disclosure Bulletins

Search:











## **Search History**

DATE: Friday, January 04, 2008 Purge Queries Printable Copy Create Case

Set Name side by side	Query	<u>Hit</u> <u>Count</u>	Set Name result set
DB = 1	PGPB, $USPT$ , $USOC$ , $EPAB$ , $JPAB$ , $DWPI$ , $TDBD$ ; $PLUR = YES$ ; $OP = ADJ$		
<u>L4</u>	L2 and amino acid	90	<u>L4</u>
<u>L3</u>	L1 and amino acid	124	<u>L3</u>
<u>L2</u>	L1 and (polishing or planarizing or cmp or planarization) with (copper or cu or tantalum or ta)	198	<u>L2</u>
<u>L1</u>	(catechol or pyrogallol or gallic acid or tannic acid or polyphenol or tannin) and abrasive and (oxidizer or oxidizing agent) and (benzotriazole or bta)	313	<u>L1</u>

END OF SEARCH HISTORY